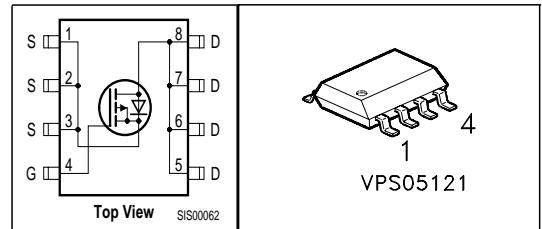


SIPMOS® Power-Transistor
Features

- P-Channel
- Enhancement mode
- Avalanche rated
- dv/dt rated
- Pb-free lead plating; RoHS compliant


Product Summary

| | | | |
|----------------------------------|--------------|-------|----------|
| Drain source voltage | V_{DS} | -60 | V |
| Drain-source on-state resistance | $R_{DS(on)}$ | 0.13 | Ω |
| Continuous drain current | I_D | -3.44 | A |



| Type | Package | Lead free |
|-------------|---------|-----------|
| BSO613SPV G | PG-SO 8 | Yes |

Maximum Ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Value | Unit |
|---|-------------------|-------------|-------------|
| Continuous drain current $T_A = 25^\circ\text{C}$ | I_D | -3.44 | A |
| Pulsed drain current $T_A = 25^\circ\text{C}$ | I_D puls | -13.8 | |
| Avalanche energy, single pulse $I_D = -3.44 \text{ A}$, $V_{DD} = -25 \text{ V}$, $R_{GS} = 25 \Omega$ | E_{AS} | 150 | mJ |
| Avalanche energy, periodic limited by T_{jmax} | E_{AR} | 0.25 | |
| Reverse diode dv/dt $I_S = -3.44 \text{ A}$, $V_{DS} = -48 \text{ V}$, $di/dt = 200 \text{ A}/\mu\text{s}$, $T_{jmax} = 150^\circ\text{C}$ | dv/dt | 6 | kV/ μ s |
| Gate source voltage | V_{GS} | ± 20 | V |
| Power dissipation $T_A = 25^\circ\text{C}$ | P_{tot} | 2.5 | W |
| Operating and storage temperature | T_j , T_{stg} | -55... +150 | °C |
| IEC climatic category; DIN IEC 68-1 | | 55/150/56 | |

Thermal Characteristics

| Parameter | Symbol | Values | | | Unit |
|--|------------|--------|------|------|------|
| | | min. | typ. | max. | |
| Characteristics | | | | | |
| Thermal resistance, junction - soldering point (Pin 4) | R_{thJS} | - | - | 25 | K/W |
| SMD version, device on PCB: @ min. footprint; $t \leq 10$ sec. @ 6 cm ² cooling area ¹⁾ ; $t \leq 10$ sec. | R_{thJA} | - | - | 100 | |
| | | - | - | 50 | |

Electrical Characteristics, at $T_j = 25$ °C, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|--|---------------|--------|------|------|------|
| | | min. | typ. | max. | |
| Static Characteristics | | | | | |
| Drain- source breakdown voltage $V_{GS} = 0$ V, $I_D = -250$ µA | $V_{(BR)DSS}$ | -60 | - | - | V |
| Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 1$ mA | $V_{GS(th)}$ | -2.1 | -3 | -4 | |
| Zero gate voltage drain current $V_{DS} = -60$ V, $V_{GS} = 0$ V, $T_j = 25$ °C $V_{DS} = -60$ V, $V_{GS} = 0$ V, $T_j = 125$ °C | I_{DSS} | - | -0.1 | -1 | µA |
| - | - | - | -10 | -100 | |
| Gate-source leakage current $V_{GS} = -20$ V, $V_{DS} = 0$ V | I_{GSS} | - | -10 | -100 | nA |
| Drain-source on-state resistance $V_{GS} = -10$ V, $I_D = -3.44$ A | $R_{DS(on)}$ | - | 0.11 | 0.13 | Ω |

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|--|---------------|---------------|-------------|-------------|-------------|
| | | min. | typ. | max. | |
| Dynamic Characteristics | | | | | |
| Transconductance $V_{DS} \geq 2^* I_D^* R_{DS(on)max}$, $I_D = -3.44 \text{ A}$ | g_{fs} | 2.2 | 4.4 | - | S |
| Input capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = -25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{iss} | - | 700 | 875 | pF |
| Output capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = -25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{oss} | - | 235 | 295 | |
| Reverse transfer capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = -25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{rss} | - | 95 | 120 | |
| Turn-on delay time $V_{DD} = -30 \text{ V}$, $V_{GS} = -10 \text{ V}$, $I_D = -3.44 \text{ A}$, $R_G = 2.7 \Omega$ | $t_{d(on)}$ | - | 10 | 15 | ns |
| Rise time $V_{DD} = -30 \text{ V}$, $V_{GS} = -10 \text{ V}$, $I_D = -3.44 \text{ A}$, $R_G = 2.7 \Omega$ | t_r | - | 11 | 16.5 | |
| Turn-off delay time $V_{DD} = -30 \text{ V}$, $V_{GS} = -10 \text{ V}$, $I_D = -3.44 \text{ A}$, $R_G = 2.7 \Omega$ | $t_{d(off)}$ | - | 32 | 48 | |
| Fall time $V_{DD} = -30 \text{ V}$, $V_{GS} = -10 \text{ V}$, $I_D = -3.44 \text{ A}$, $R_G = 2.7 \Omega$ | t_f | - | 12 | 18 | |

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|------------------|---------------|---------------|-------------|-------------|-------------|
| | | min. | typ. | max. | |

Dynamic Characteristics

| | | | | | |
|--|------------------------|---|-------|-----|----|
| Gate to source charge $V_{DD} = -48 \text{ V}, I_D = -3.44 \text{ A}$ | Q_{gs} | - | 1.6 | 2.4 | nC |
| Gate to drain charge $V_{DD} = -48 \text{ V}, I_D = -3.44 \text{ A}$ | Q_{gd} | - | 10 | 15 | |
| Gate charge total $V_{DD} = -48 \text{ V}, I_D = -3.44 \text{ A}, V_{GS} = 0 \text{ to } -10 \text{ V}$ | Q_g | - | 20 | 30 | |
| Gate plateau voltage $V_{DD} = -48 \text{ V}, I_D = -3.44 \text{ A}$ | $V_{(\text{plateau})}$ | - | -3.74 | - | V |

| Parameter | Symbol | Values | | | Unit |
|------------------|---------------|---------------|-------------|-------------|-------------|
| | | min. | typ. | max. | |

Reverse Diode

| | | | | | |
|--|----------|---|-------|-------|----|
| Inverse diode continuous forward current $T_A = 25^\circ\text{C}$ | I_S | - | - | -3.44 | A |
| Inverse diode direct current,pulsed $T_A = 25^\circ\text{C}$ | I_{SM} | - | - | -13.8 | |
| Inverse diode forward voltage $V_{GS} = 0 \text{ V}, I_F = -3.44 \text{ A}$ | V_{SD} | - | -0.87 | -1.16 | V |
| Reverse recovery time $V_R = -30 \text{ V}, I_F = I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$ | t_{rr} | - | 56 | 84 | ns |
| Reverse recovery charge $V_R = -30 \text{ V}, I_F = I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$ | Q_{rr} | - | 38 | 57 | nC |

BSO613SPV G